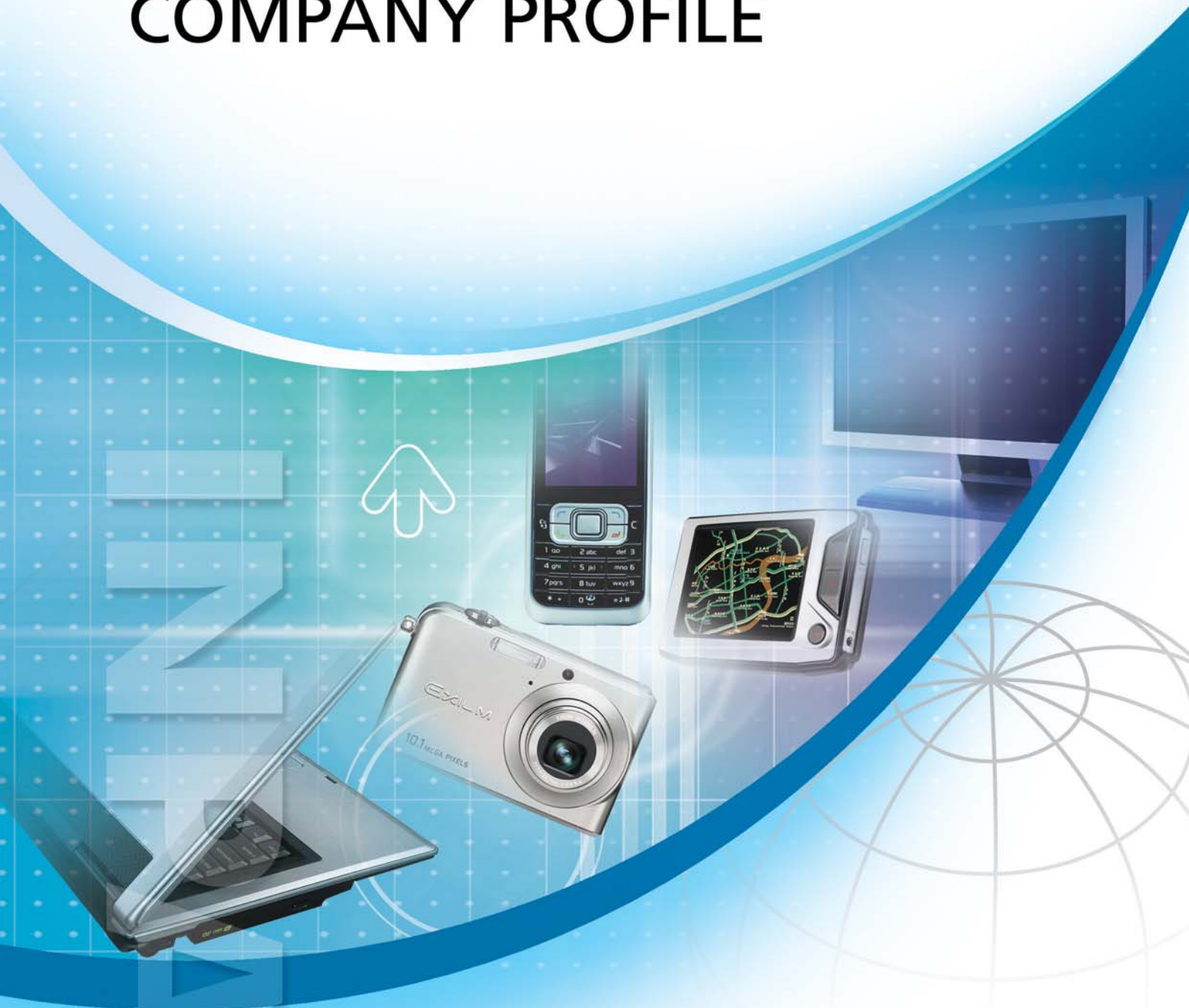




COMPANY PROFILE



ISO9001
TS16949
ISO14001



Company owned Manufacturing

Processing Technology

- Multilayer
- Thick Film
- Thin Film
- Integration
- PCB processes on Polymer
- Module Design & Assembly

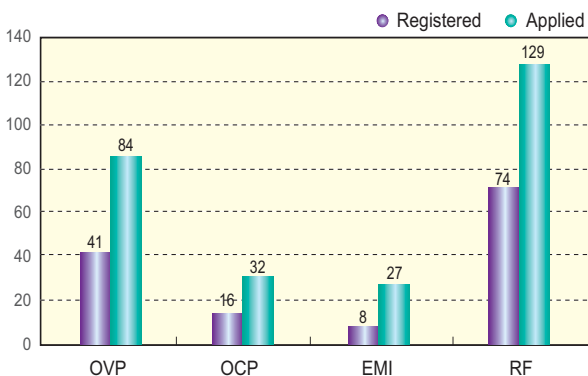
Material Technology

- Thick Film
 - Conducting, resistance, dielectric paste
 - Process and material optimization
- Ceramic
 - Dielectric, Varistor, Ferrite Ceramic
- Polymer
 - Protective material
 - Conducting polymer material
- Silicon

Environment / Safety and Health Policy

- Devote to environmental responsibility
- Concern about employees' safety and health

Intellectual Property Rights



Registered Total: 139
Applied Total: 272

Milestones

- 1998**
 - INPAQ established
 - Capacitor Array (CN41 Series) production
- 1999**
 - ISO-9001, QS-9000 & IECQ Certification
 - GPS Patch Antenna (PA Series) and MLV (MLV Series) production
- 2000**
 - Multilayer Chip Capacitor Array (CA41 Series) production
 - GPS Active Antenna (GPS Series) production
- 2001**
 - INPAQ Technology (Suzhou) established
 - PPTC, ESD Guard™ released
- 2002**
 - Headquarters move to Science-Based Industrial Park
- 2003**
 - ISO-14001 Certification
 - Green Partner (Sony SS-00259) Certified
- 2004**
 - **IPO in Taiwan Stock Market (6284)**
- 2005**
 - Samsung Green Management System Certification
 - ISO/TS16949: 2002 Certification
 - Merger of E-Tronic Corporation
 - LC Filter (LFA Series) released
- 2006**
 - New production facility in operation in Chunan, Miaoli County, Taiwan
 - TS 16949 Certification
- 2007**
 - INPAQ Technology (Korea) established
- 2008**
 - Multilayer Power Inductor production
 - DIP Molding Type Power Inductor production
 - SMD Type Power Inductor production
 - Aluminum Solid Electrolytic Capacitor production
- 2009**
 - TVL0402/0201 production
 - GPS (ACD5036) and BT (ACA5036) Coupling type chip antenna production
 - New production facility in Wuxi, China
 - QC080000 Certification
- 2010**
 - OHSAS18001 Certification by UL in January

R&D Center

Developing new technologies is one of INPAQ's core competencies. With continuous investments in R&D for new products, INPAQ is well prepared to meet customer's future needs. Our proven record of innovation has contributed to our customers success.

Our expertise and experience in material science, process technology and automation gives INPAQ the capability to respond to the changing demands of the market quickly.

INPAQ supports their customers with 4 laboratories in Taiwan and China including Sales and FAE support in Taiwan, China, Korea & North America.

Quality / HSF Commitment

In order to provide our customers with the highest quality and HSF products, our commitment to customers is to give continuous improvement in manufacturing process, product development and quality.



ISO/TS 16949



ISO 9001



ISO 14001



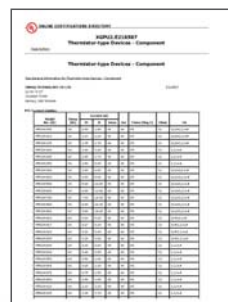
QC 080000



Approval of Manufacturer
By IECQ



Product Safety Assurance
By TÜV



Product Safety Assurance
By UL



National Standardization Award
By M.O.E.A., R.O.C.

Design
Manufacturing

About INPAQ

INPAQ Technology Corporation researches, designs, manufactures and markets a wide range of Integrated Passive Components, including EMI/EMC Solution, Over Voltage Protection, Over Current Protection, and RF Antenna products.

Our core competence is to supply a total solution from material composition, product design, research & development, manufacturing and marketing, that can bring suitable solutions to meet customers' special requirements.

Our goal is not only to improve core competence and continuously expand business capability, focusing on enhancing customer satisfaction, but also to provide customers with more responsive service and support activities.

Our commitment to achieve the highest efficiency, reliability and cost effectiveness allows INPAQ to grow consistently in the competitive marketplace and to take the major lead in advanced electronic and RF components.

Our Philosophy

- Innovation
- Nature
- People
- Advance
- Quality



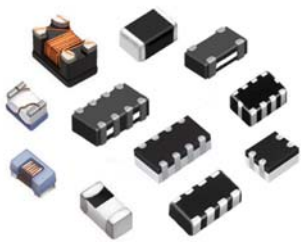
Computer



Communication



COMPONENT



EMI / EMC Solution

● EMI Filter

- LC Filter Array-LFA Series
- Thin Film Common Mode Filter-TCF Series
- Chip Common Mode Filter-MCM Series
- Chip Common Mode Filter Array-MCA Series
- Wire-wound Common Mode Filter-WCM Series

● Multilayer Chip Inductor

- Chip Ferrite Inductor-MFI Series
- High Frequency Chip Ceramic Inductor-MCI Series
- Wire-wound Ceramic Chip Inductor-WCI Series

● Multilayer Chip Bead

- Chip Ferrite Bead for GHz Range-MGB Series
- Chip Ferrite Bead-MCB-S/B Series
- Chip Ferrite Bead For High Speed-MCB-H/U Series
- High Current Chip Ferrite Bead-MHC Series
- Chip Ferrite Bead Array-M4A-S Series



Circuit Protection

● ESD Guard™

- EGA Series
- EGA Array Series

● Multilayer Varistor

- MLVS Series
- MLVG Series
- MLV Array Series

● EMI / ESD Suppressor

- VPORT Series

● Transient Voltage Suppressor

- TVS Diode

● ESD Array Series

- TVU Series



Power Solution

● Multilayer Power Inductor

- MIP Series

● SMD Type Power Inductor

- SPI, SMP Series

● Molding Type Power Inductor

- DMP Series

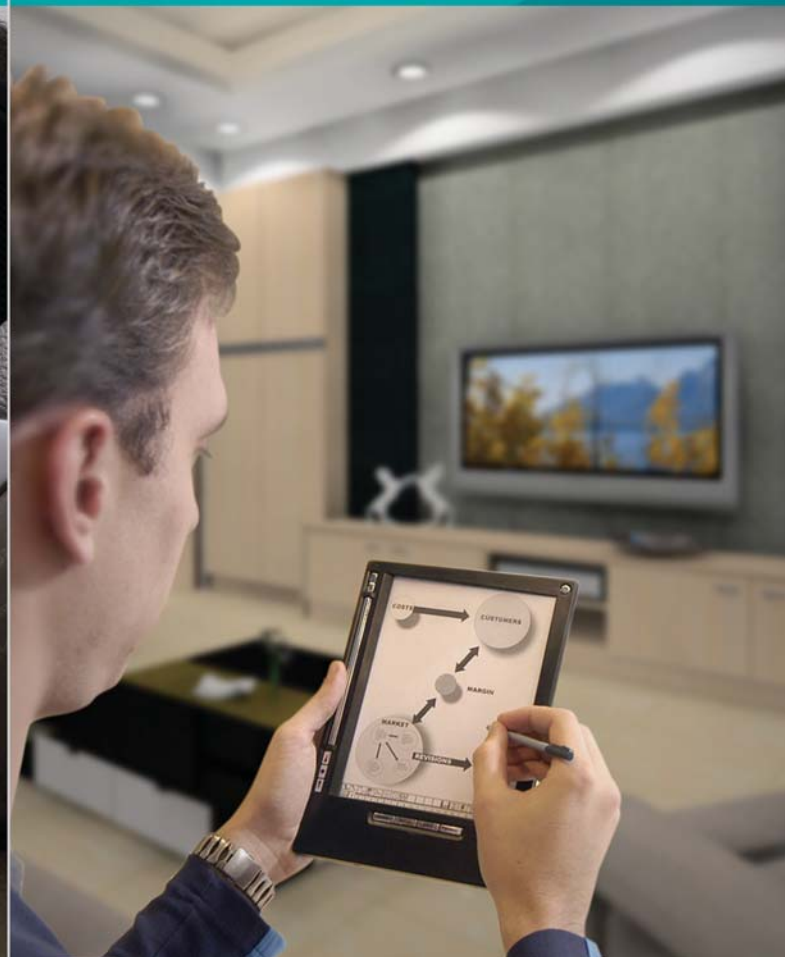
● SMD Type Power Inductor

- IPI, IPC Series

Automotive



Consumer Electronics

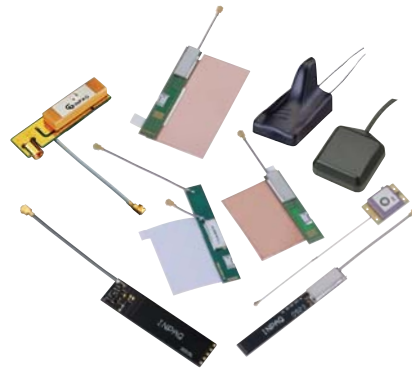


RF ANTENNA



● Patch Antenna

- GPS
- SDARS



● Active Antenna

- External GPS
- GPS
- GPS/WLAN Combo
- Digital TV
- External SDARS
- External GPS/GSM Combo



● Chip Antenna

- GPS
- GPS/2.4GHz Combo
- 2.4GHz ISM Band
- FM



● Customized Antenna

- Notebook & Cellular Phone

INPAQ Products

Item	Category	Product Name	Series	Size(EIA)	Size(EIAJ)		
Component	EMI EMC Solution	LC Filter Array	LFA	0805	2012		
		Thin Film Common Mode Filter	TCF	0504	1210		
				0804	2010		
		Chip Common Mode Filter (B type)	MCM	0405	1012		
				0805	2012		
				0508	1220		
		Chip Common Mode Filter Array	MCA	0805	2012		
				1206	3216		
		Wire-wound Common Mode Filter	WCM	0805	2012		
		Chip Ferrite Inductor	MFI	0603	1608		
				0805	2012		
				1206	3216		
		High Frequency Chip Ceramic Inductor	MCI	0201	0603		
				0402	1005		
				0603	1608		
		Wire-wound Ceramic Chip Inductor	WCI	0402	1005		
		Chip Ferrite Bead for GHz Range	MGB	0402	1005		
		Chip Ferrite Bead (S Series, B Series, H Series, U series)	MCB	0201	0603		
				0402	1005		
				0603	1608		
				0805	2012		
				1206	3216		
				1210	3225		
				1806	4516		
				1812	4532		
		High Current Chip Ferrite Bead	MHC	0402	1005		
				0603	1608		
				0805	2012		
	1206			3216			
	1210			3225			
	1806			4516			
	1812			4532			
	Chip Ferrite Bead Array (S series)	M4A	0804	2010			
			1206	3216			
	Circuit Protection	ESD Guard™	EGA	0402	1005		
				0603	1608		
		Multilayer Varistor	MLVS	1206	3216		
				0201	0603		
				0402	1005		
				0603	1608		
				1206	3216		
				0402	1005		
				0603	1608		
				0805	2012		
	EMI/ESD Suppressor	VPORT	0402	1005			
	Transient Voltage Suppressor	TVS	0603	1608			
	ESD Array Series	TVU	1004	2510			
	Power Solution	Description		Series	Size(EIA)	Size(EIAJ)	
		Multilayer Power Inductor		MIP	1008	2520	
		Description		Series	Size(EIA)	Size(EIAJ)	
		SMD Type Power Inductor	SPI, SMP	0603	SPI0703AR		
				1004	SPI1004AR		
1203				SMP1203W			
Molding Type Power Inductor		DMP	0808	DMP0808HBAA DMP0808HBA			
			1010	DMP1009HHAA DMP1009HHHA			
			1110	DMP1109HJAA DMP1109HJA			
			1210	DMP1209HLAA DMP1209HLA			
Description		Series	Dimension Size(mm)	Height			
SMD Type Power Inductor		IPI, IPC	3.0 x 3.0	IPC3010F	IPI2D11N IPC3012F	IPI2D14N IPC3015F	IPI2D18N IPC3020F
			4.0 x 4.0	IPC4010F	IPI3D11N IPC4012F	IPI3D14N IPC4015F	IPI3D16N IPC4018F
			5.0 x 5.0	IPC5010F	IPI4D11N IPC5012F	IPI4D14N IPC5015F	IPI4D18N IPC5020F
Item		Category	Product Name			Series	
RF Antenna	Patch Antenna	GPS			PA1575MZ50I4G-XX-17		
					PA1575MZ50I2G-XX-17		
					PA1575MZ50J4G-XX-16		
					PA1575MZ50J2G-XX-16		
					PA1575MZ50K4G-XX-21		
					PA1575MZ50Q4G-XX-21		
					PA1575MZ50R4G-XX-2N		
					LA1575MK4G-XXX-XX		
	Chip Antenna	GPS			PAS2326MZ50H4G		
					PAS2339MZ50H4G		
					ACD-5036-A3-CC-S		
					ACM0-9025-A1-CC-S		
	Active Antenna	2.4GHz ISM Band			ACA-5020-A2-MC-S		
					ACA-3216-A2-MC-S		
					ACA-5036-A2-CC-S		
	Customized Antenna	Notebook & Cellular Phone			FM		
					FMCN2F100G		
					GPS03B-D3/D5-XX-A		
					GPS10D-D3/D5-XX-A		
GPS316K-S3/S5-XX-A							
GPS174N-S3-01-A							
GPS338N-S3-00-A							
GPS351N-S3-00-A							
GPS356N-S3-00-A							
GPS/WLAN Combo	GPSWLAN05N-S3-01-A						
Digital TV	ACT1-4010-A1-MF-S						
External SDARS	ACT1-5006-A1-MF-S						
External GPS/GSM Combo	SI00K-D5-00-A						
External GPS/GSM Combo	GPS01F-S4-XX-A						
External GPS/GSM Combo	GPS02F-S4-XX-A						
External, Internal, Retractable							



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